

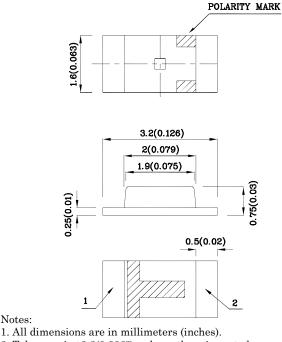
3.2mmx1.6mm SMD CHIP LED LAMP

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Features

- Ideal for indication light on hand held products
- Long life and robust package
- Variety of lens types and color choices available
- Package : 2000pcs / reel
- Moisture sensitivity level : level 3
- RoHS compliant





Package Schematics

2. Tolerance is $\pm 0.2(0.008")$ unless otherwise noted.

3. Specifications are subject to change without notice.

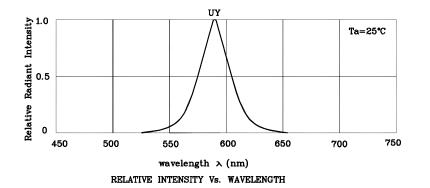
Absolute Maximum Ratings (T _A =25°C)		UY (GaAsP/GaP)	Unit
Reverse Voltage	$V_{\rm R}$	5	V
Forward Current	I_{F}	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	ifs	140	mA
Power Dissipation	\mathbf{P}_{D}	75	mW
Operating Temperature	$T_{\rm A}$	$-40 \sim +85$	°C
Storage Temperature	Tstg	-40 ~ +85	-C

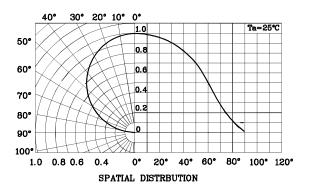
Operating Characteristics (T _A =25°C)		UY (GaAsP/GaP)	Unit
Forward Voltage (Typ.) (I _F =20mA)	$V_{\rm F}$	2.1	V
Forward Voltage (Max.) (I _F =20mA)	V_{F}	2.5	V
Reverse Current (Max.) (V _R =5V)	I_R	10	uA
Wavelength of Peak Emission (Typ.) (I _F =20mA)	λP	590	nm
Wavelength of Dominant Emission (Typ.) (I _F =20mA)	λD	588	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =20mA)	$ riangle\lambda$	35	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	С	20	pF

Part Number	Emitting Color	Emitting Material	Lens-color	Luminous Intensity (I _F =20mA) mcd		Wavelength nm λP	Viewing Angle 20 1/2
				min.	typ.		
XZUY55W-1	Yellow	GaAsP/GaP	Water Clear	5	7	590	120°

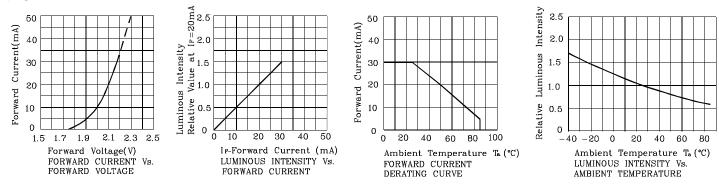
XDSA1328 V6 Layout: Maggie L.











LED is recommended for reflow soldering and soldering profile is shown below.

Reflow Soldering Profile for SMD Products (Pb-Free Components)

300 (°C) 10 s max 250 4°C/s C/s max 200 150~180 4°C/s max 150 Temperature 30~50s 80~120: 100 50 0 150 0 50 100 200 250 300 (sec) Time Notes: 1. Maximum soldering temperature should not exceed 260°C

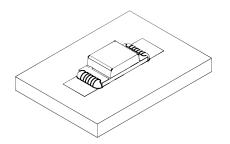
Maximum soldering temperature should not exceed 200°C
Recommended reflow temperature: 145°C-260°C

3. Do not put stress to the epoxy resin during

high temperatures conditions



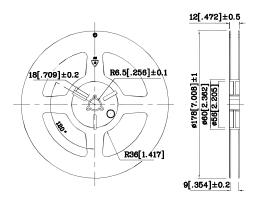
✤ The device has a single mounting surface. The device must be mounted according to the specifications.



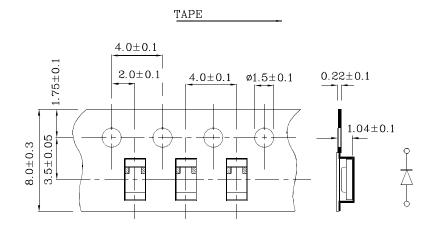
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



Reel Dimension



Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, Luminous intensity / luminous flux, or wavelength),

the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm

2. Luminous intensity / luminous flux: +/-15%

3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.

Apr 11,2011



PACKING & LABEL SPECIFICATIONS

